

■ Features

High Output Power: P5dB=45.0dBm (Typ.)

• High Linear Gain: GL=14.0dB (Typ.)

• High Power Added Efficiency: PAE=44% (Typ.)

• Broad Band: 7.7 to 8.5GHz

• Impedance Matched Zin/Zout = 50ohm

· Hermetically Sealed Package

Description

The SGK7785-30C is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.



ABSOLUTE MAXIMUM RATING (Case Temperature T_c=25 deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	26	V
Gate-Source Voltage	V _{GS}	-10	V
Total Power Dissipation	P _T	86.5	W
Storage Temperature	T _{stg}	-55 to +125	deg.C
Channel Temperature	T _{ch}	+250	deg.C
Case Temperature	T _c	-40 to +125	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V_{DS}		<=24	V
Forward Gate Current	I_{GF}	Rg=100ohm	<=4.4	mA
Reverse Gate Current	I_{GR}	Rg=100ohm	>=-2.3	mA
Channel Temperature	T _{ch}		<+193	deg.C

ELECTRICAL CHARACTERISTICS (Case Temperature T_c=25 deg.C)

Thom	Cumbal	ool Condition		Limit			
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Saturated Drain Current	I_{DSS}	V _{DS} =10V, V _{GS} =0V	-	8.3	-	Α	
Trans Conductance	G _m	V _{DS} =24V, I _{DS} =0.96A	-	2.2	-	S	
Pinch-off Voltage	V_P	V _{DS} =24V, I _{DS} =0.96mA	-2.5	-4.0	-5.5	V	
Output Power at 5dB G.C.P.	P _{5dB}		44.0	45.0	-	dBm	
Linear Gain at Pin=23dBm	GL	V _{DS} =24V(typ.)	11.0	14.0	-	dB	
Drain Current at 5dB G.C.P.	I_{DSR}	I _{DS(DC)} =1.75A(typ.) f=7.7 to 8.5 GHz	-	3.2	4.0	А	
Power Added Efficiency at 3dB G.C.P.	PAE	Vgs-constant	-	44.0	-	%	
Gain Flatness	ΔG	vgs constant	-	-	1.2	dB	
3rd Order Inter Modulation Distortion	IM ₃	f=8.5GHz Δf=10MHz, 2-tone Test Pout=29.5dBm (S.C.L.)	-40.0	-42.0	-	dBc	
Thermal Resistance	R _{th}	Channel to Case	-	2.2	2.6	deg.C/W	
Channel Temperature Rise	ΔT_{ch}	(V _{DS} x I _{DSR} - Pout + Pin) x R _{th}	-	83	150	deg.C	

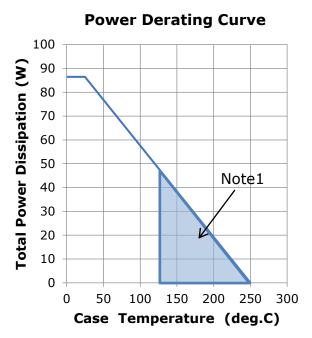
G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level

CASE STYLE	IBK	
RoHS Compliance	YES	
ESD *1	Class 2	2000V to < 4000V

Note: *1 Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

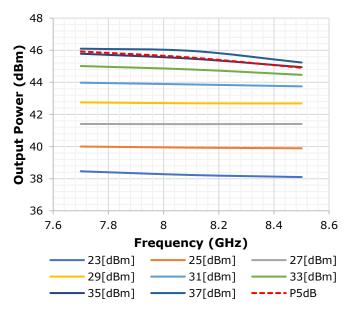


RF Characteristics

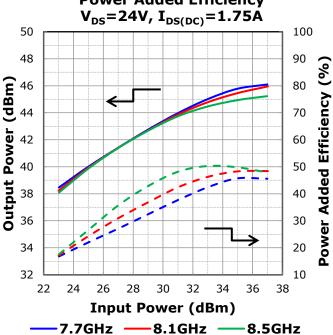


Note 1: Shaded area exceeds Maximum Case Operating Temperature (See Page1)

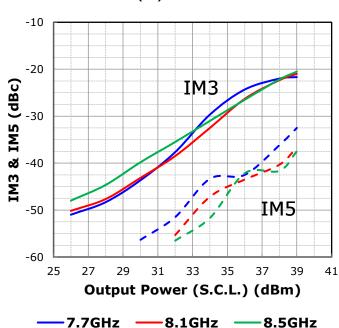
Output Power vs. Frequency $V_{DS} = 24V, I_{DS(DC)} = 1.75A$



Input Power vs. Output Power and Power Added Efficiency



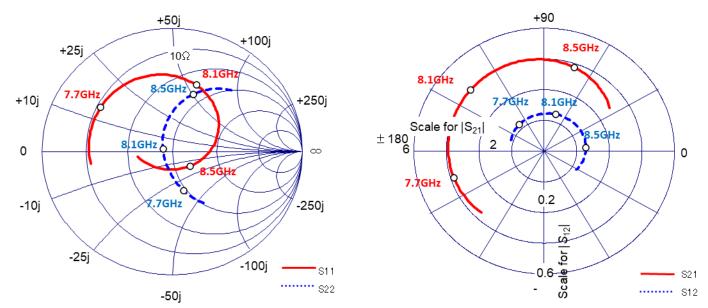
IMD vs. Output Power (S.C.L.) $V_{DS} = 24V$, $I_{DS(DC)} = 1.75A$, $\Delta f = 10MHz$



8.5GHz



• S-Parameter



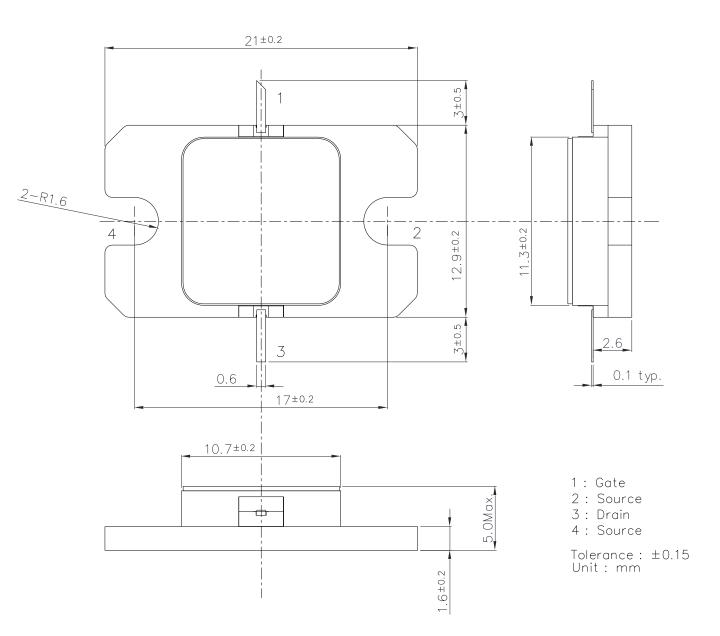
Bias Condition V_{DS} =24V, $I_{DS(DC)}$ =1.75A Rg = 100ohm

Freq. S11			S21		S12		S22	
		ANG	MAG	ANG	MAG	ANG	MAG	ANG
7.5GHz	0.633	-171.2	5.545	-133.9	0.081	160.0	0.482	-59.8
7.6GHz	0.646	167.4	5.694	-148.3	0.084	146.2	0.408	-67.2
7.7GHz	0.656	146.7	5.809	-162.7	0.086	131.8	0.329	-74.5
7.8GHz	0.657	127.2	5.882	-177.2	0.088	117.9	0.249	-83.1
7.9GHz	0.644	108.3	5.931	168.4	0.090	103.6	0.169	-95.2
8.0GHz	0.617	90.0	5.982	153.7	0.092	88.9	0.095	-123.5
8.1GHz	0.572	71.2	6.025	138.7	0.094	73.7	0.073	164.7
8.2GHz	0.503	51.6	6.051	123.1	0.095	57.9	0.148	118.2
8.3GHz	0.412	29.7	6.046	106.7	0.097	41.0	0.254	98.5
8.4GHz	0.296	2.5	5.967	89.4	0.097	23.8	0.373	84.1
8.5GHz	0.180	-40.4	5.765	71.4	0.097	5.4	0.493	70.9
8.6GHz	0.158	-118.0	5.398	53.0	0.093	-13.4	0.602	58.0
8.7GHz	0.270	-170.9	4.907	34.9	0.087	-31.5	0.686	45.7



• Package Out line

Case Style: IBK





For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
 This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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